



## Advance Product Change Notification

201708003A

**Issue Date:** 16-Sep-2017

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# QUALITY

### Management Summary

Assembly transfer of the MMA865x family from Amkor Korea (ATK1) to ASE-Chungli Taiwan (ASECL) assembly site for continuous customer supply.

### Change Category

<input type="checkbox"/> Wafer Fab Process	<input checked="" type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Location	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Process	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input checked="" type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Electrical spec./Test coverage

## MMA865x ASECL Transfer and Copper Wire Qualification

### Details of this Planned Change

NXP Semiconductors announces the assembly transfer of the MMA865x family to the ASE-Chungli Taiwan (ASECL) assembly site. These products were previously assembled at the Amkor Korea (ATK1) assembly site.

With this change, NXP Semiconductors also announces the materials change to Gold Palladium Copper (AuPdCu) wire, Sumitomo EME-G700LA mold compound, Ablestik Die Attach Film (DAF) ATB-125 and Mitsui Rough Palladium Pre-plated Frame (PPF) with Nickel Palladium Gold (NiPdAu) C7025 material for the MMA865x family of devices. These products were previously assembled with Gold (Au) wire, Sumitomo EME-G700 mold compound, Ablestik ATB-120A DAF and C7025 Ru PPF material. Qualification data will be available after qualification completion in October 2017.

Due to limited supply of the current inventory, the PCN will have an accelerated effective date of 7 days from the final PCN issue date.

### Why do we Plan this Change

The transfer to ASECL is for supply continuity as a result of ATK1 closure. The transfer from Gold to Gold Palladium Copper wire is an alignment to industry standard convention for wirebond material type. The change to mold compound and die attach material for DFN 2x2 package is required to standardize the bill of materials for ASECL assembly production.

### Identification of Affected Products

Product identification does not change

There is no change to the orderable part numbers. NXP will have traceability of the assembly site by the 2nd digit of the tracecode.

## Product Availability

### Sample Information

Samples are available from

Samples available for MMA8652 and MMA8653 with special marking for customer evaluation.

### Production

Planned first shipment 30-Oct-2017

## Impact

no impact to the product's functionality anticipated.

No impact to product form, fit, function or reliability is expected.

### Data Sheet Revision

No impact to existing datasheet

### Disposition of Old Products

Existing inventory will be shipped until depleted

## Timing and Logistics

The Self Qualification Report will be ready on 20-Oct-2017.

The Final PCN is planned to be issued on: 27-Oct-2017.

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 16-Oct-2017.

## Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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**Position** Product Engineer

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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

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### Affected Part Numbers

MMA8652FCR1

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